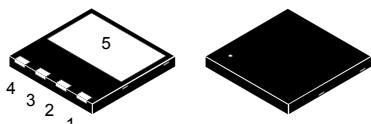
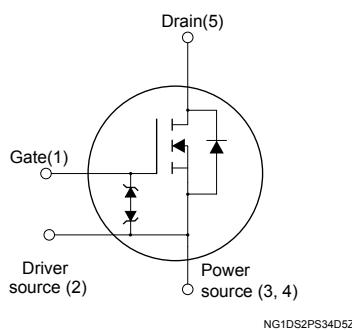


## N-channel 600 V, 0.278 Ω typ., 11 A MDmesh M2 Power MOSFET in a PowerFLAT 8x8 HV package

### Features



**PowerFLAT 8x8 HV**



Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STL19N60M2	600 V	0.308 Ω	11 A

- Extremely low gate charge
- Excellent output capacitance (Coss) profile
- 100% avalanche tested
- Zener-protected

### Applications

- Switching applications

### Description

This device is an N-channel Power MOSFET developed using MDmesh M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.



#### Product status link

[STL19N60M2](#)

#### Product summary

<b>Order code</b>	STL19N60M2
<b>Marking</b>	19N60M2
<b>Package</b>	PowerFLAT 8x8 HV
<b>Packing</b>	Tape and reel

## 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_C = 25^\circ\text{C}$	11	A
$I_D$	Drain current (continuous) at $T_C = 100^\circ\text{C}$	6.9	A
$I_{DM}^{(1)}$	Drain current (pulsed)	44	A
$P_{TOT}$	Total power dissipation at $T_C = 25^\circ\text{C}$	90	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15	V/ns
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	50	V/ns
$T_{stg}$	Storage temperature range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating junction temperature range		

1. Pulse width limited by safe operating area.
2.  $I_{SD} \leq 11 \text{ A}$ ,  $di/dt \leq 400 \text{ A}/\mu\text{s}$ ;  $V_{DS(\text{peak})} < V_{(BR)DSS}$ ,  $V_{DD} = 400 \text{ V}$ .
3.  $V_{DS} \leq 480 \text{ V}$ .

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	1.39	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	45	$^\circ\text{C}/\text{W}$

1. When mounted on FR-4 board of  $\text{inch}^2$ , 2oz Cu.

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not repetitive (pulse width limited by $T_J$ max)	3	A
$E_{AS}$	Single pulse avalanche energy (starting $T_J = 25^\circ\text{C}$ , $I_D = I_{AR}$ ; $V_{DD} = 50 \text{ V}$ )	135	mJ

## 2 Electrical characteristics

$T_C = 25^\circ\text{C}$  unless otherwise specified

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	600			V
$I_{\text{DSS}}$	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}, T_C = 125^\circ\text{C}$ (1)			100	$\mu\text{A}$
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{D\text{S(on)}}$	Static drain-source on-resistance	$V_{GS} = 10 \text{ V}, I_D = 5.5 \text{ A}$		0.278	0.308	$\Omega$

- Defined by design, not subject to production test.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance		-	791	-	pF
$C_{oss}$	Output capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	40	-	pF
$C_{rss}$	Reverse transfer capacitance		-	1.3	-	pF
$C_{oss \text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0 \text{ to } 480 \text{ V}, V_{GS} = 0 \text{ V}$	-	164.5	-	pF
$R_G$	Intrinsic gate resistance	$f = 1 \text{ MHz}, I_D = 0 \text{ A}$	-	5.6	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 13 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$	-	21.5	-	nC
$Q_{gs}$	Gate-source charge	(see Figure 14. Test circuit for gate charge behavior)	-	3.2	-	nC
$Q_{gd}$	Gate-drain charge		-	11.3	-	nC

- $C_{oss \text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(\text{on})}$	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 6.5 \text{ A}$	-	12	-	ns
$t_r$	Rise time	$R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 13. Switching times test circuit for resistive load and Figure 18. Switching time waveform)	-	9	-	ns
$t_{d(\text{off})}$	Turn-off delay time		-	47	-	ns
$t_f$	Fall time		-	10.6	-	ns

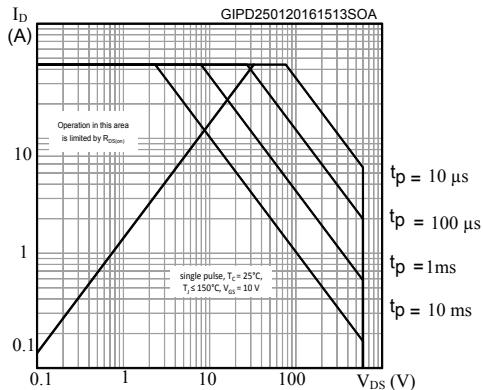
Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		11	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		44	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0 \text{ V}$ , $I_{SD} = 11 \text{ A}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 13 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ ,	-	305		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60 \text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times )	-	3.3		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	22		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 13 \text{ A}$ , $dI/dt = 100 \text{ A}/\mu\text{s}$ ,	-	417		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60 \text{ V}$ , $T_J = 150 \text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	4.6		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	22		A

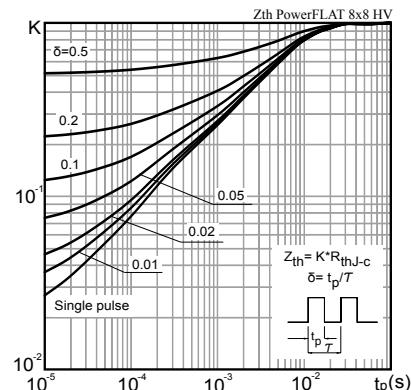
1. Pulse width is limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

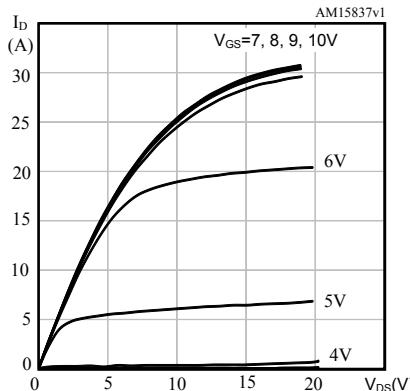
**Figure 1. Safe operating area**



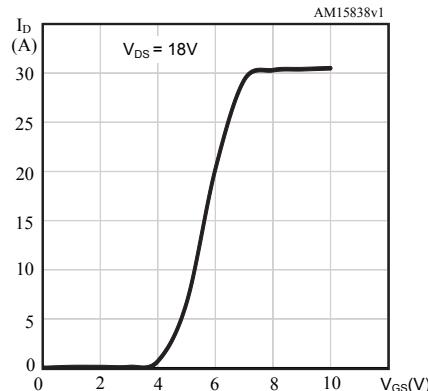
**Figure 2. Thermal impedance**



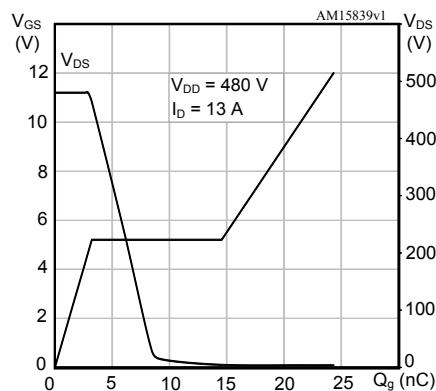
**Figure 3. Output characteristics**



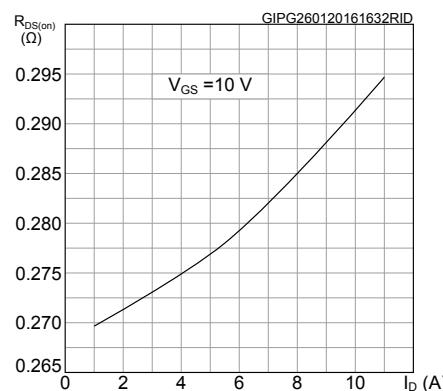
**Figure 4. Transfer characteristics**

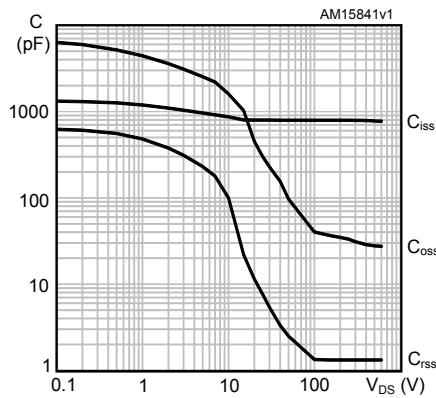
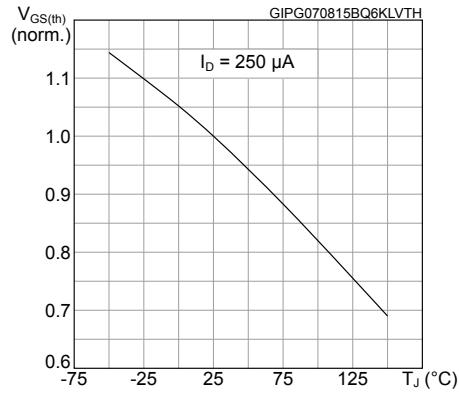
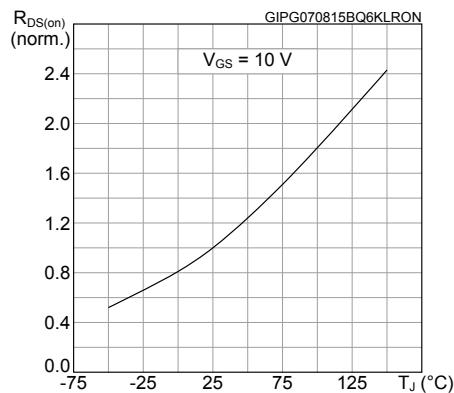
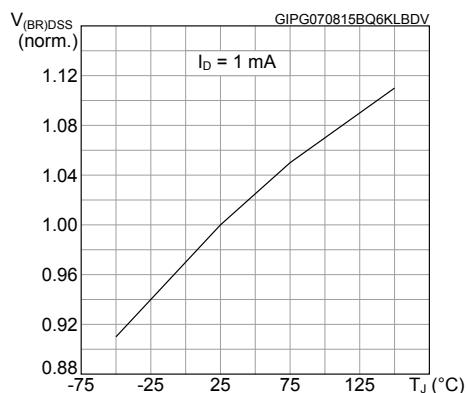
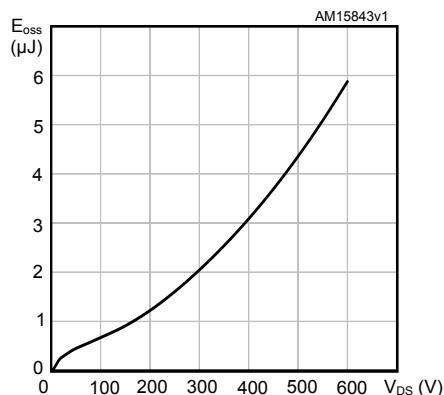
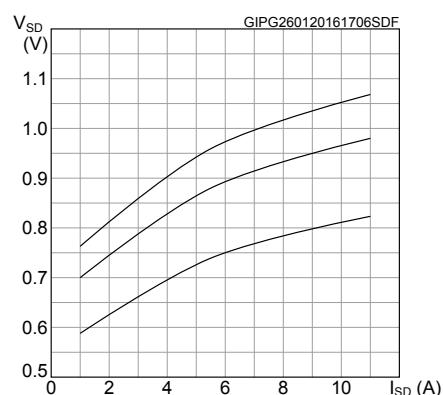


**Figure 5. Gate charge vs gate-source voltage**



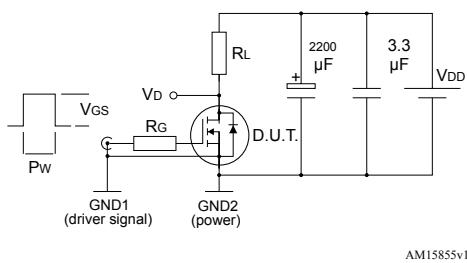
**Figure 6. Static drain-source on-resistance**



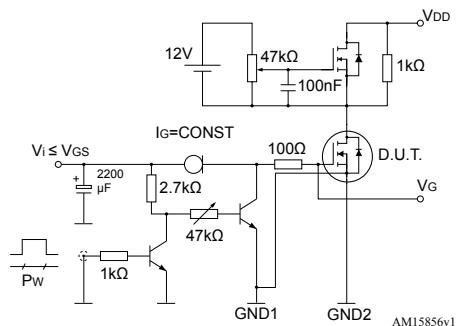
**Figure 7. Capacitance variations**

**Figure 8. Normalized gate threshold voltage vs temperature**

**Figure 9. Normalized on-resistance vs temperature**

**Figure 10. Normalized V\_(BR)DSS vs temperature**

**Figure 11. Output capacitance stored energy**

**Figure 12. Source-drain diode forward characteristics**


### 3 Test circuits

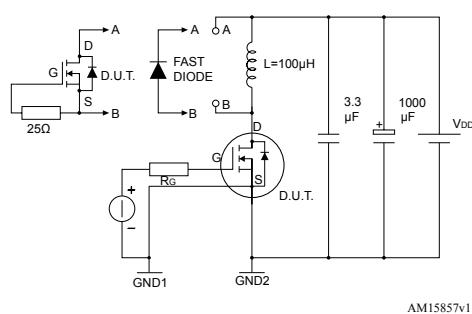
**Figure 13.** Switching times test circuit for resistive load



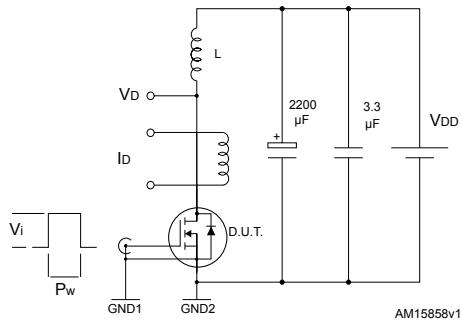
**Figure 14.** Test circuit for gate charge behavior



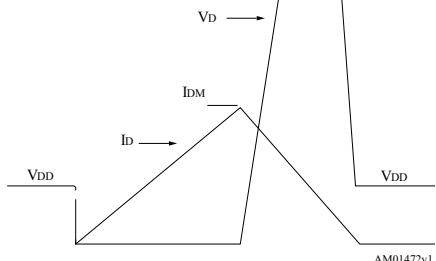
**Figure 15.** Test circuit for inductive load switching and diode recovery times



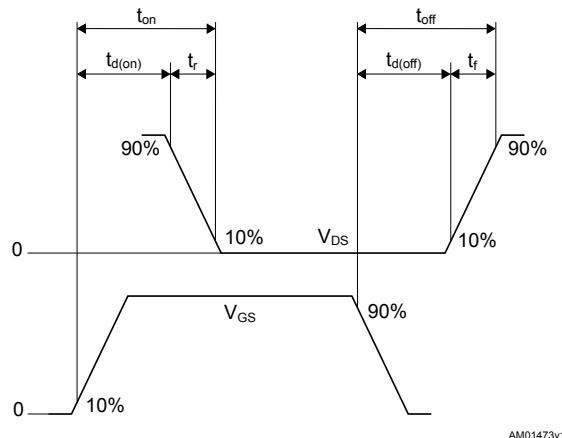
**Figure 16.** Unclamped inductive load test circuit



**Figure 17.** Unclamped inductive waveform



**Figure 18.** Switching time waveform

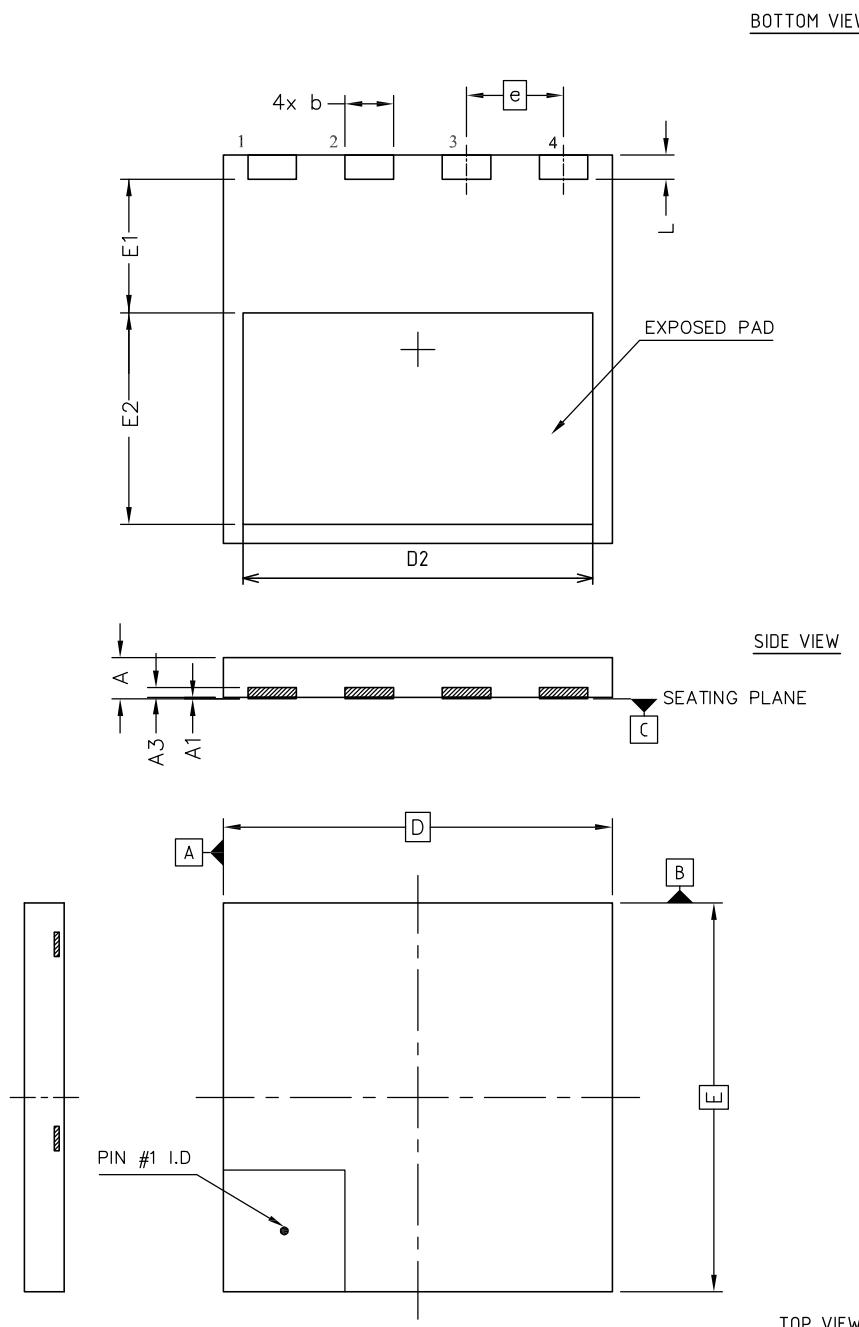


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 PowerFLAT 8x8 HV package information

Figure 19. PowerFLAT 8x8 HV package outline

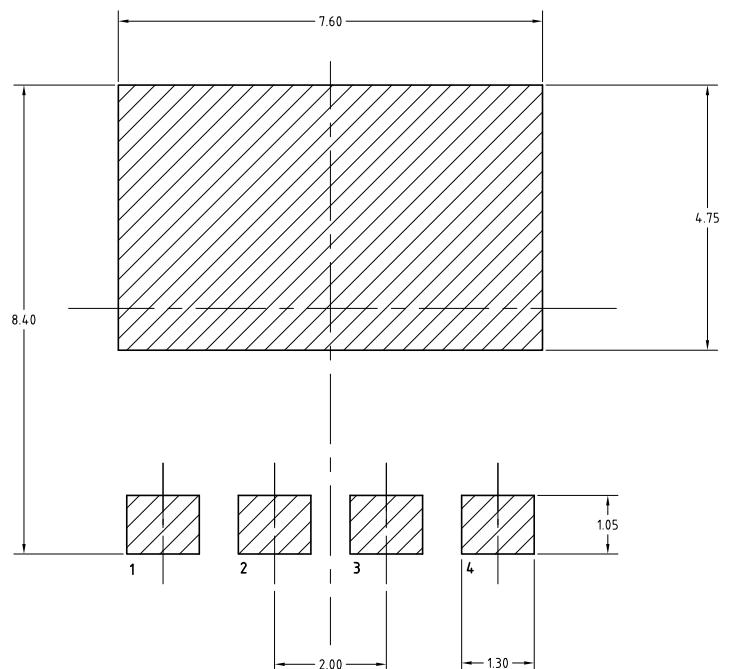


8222871\_Rev\_4

Table 8. PowerFLAT 8x8 HV mechanical data

Ref.	Dimensions (in mm)		
	Min.	Typ.	Max.
A	0.75	0.85	0.95
A1	0.00		0.05
A3	0.10	0.20	0.30
b	0.90	1.00	1.10
D	7.90	8.00	8.10
E	7.90	8.00	8.10
D2	7.10	7.20	7.30
E1	2.65	2.75	2.85
E2	4.25	4.35	4.45
e		2.00 BSC	
L	0.40	0.50	0.60

Figure 20. PowerFLAT 8x8 HV footprint

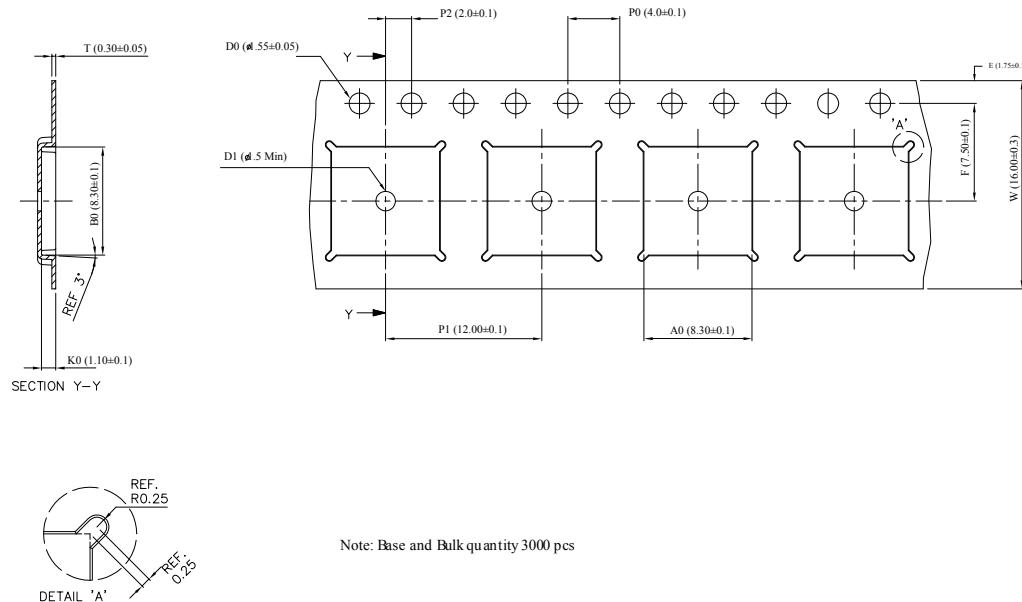


8222871\_REV\_4\_footprint

Note: All dimensions are in millimeters.

## 4.2 PowerFLAT 8x8 HV packing information

Figure 21. PowerFLAT 8x8 HV tape



Note: All dimensions are in millimeters.

Figure 22. PowerFLAT 8x8 HV package orientation in carrier tape

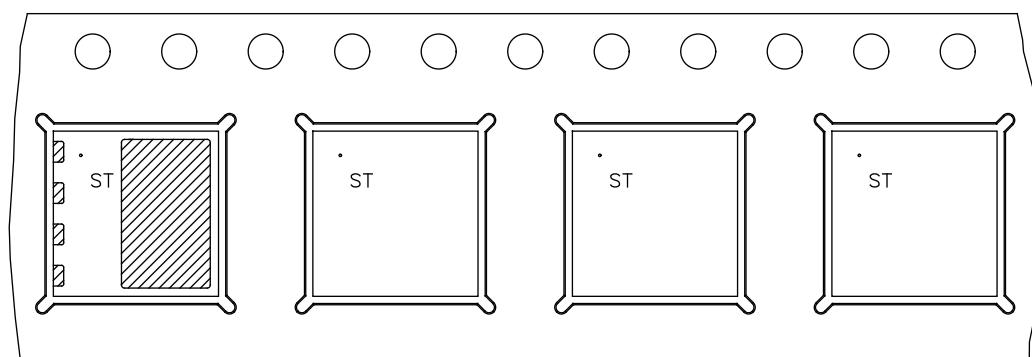
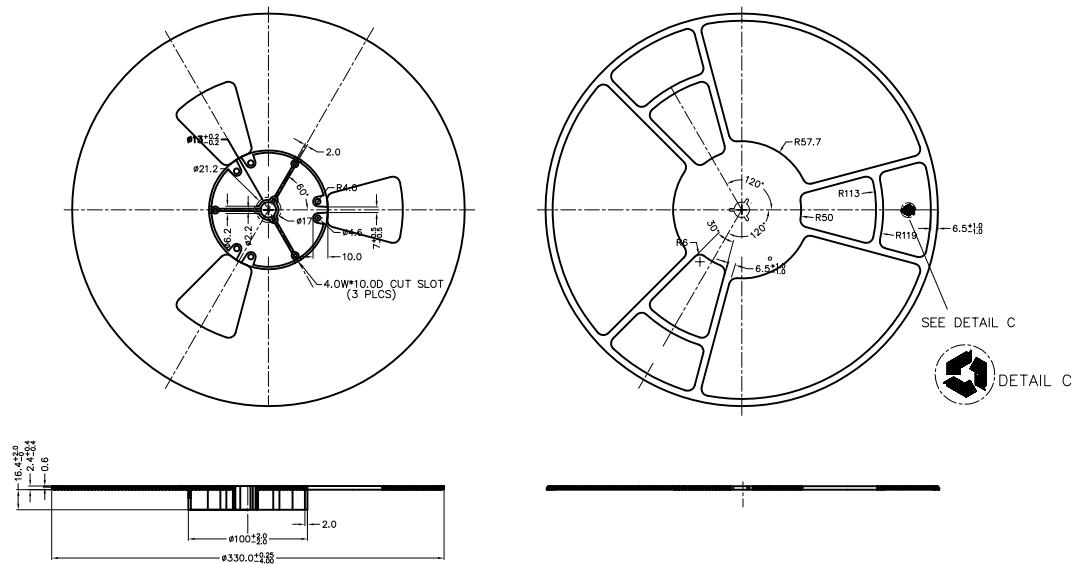


Figure 23. PowerFLAT 8x8 HV reel



8229819\_Reel\_revA

Note: All dimensions are in millimeters.

## Revision history

**Table 9. Document revision history**

Date	Revision	Changes
27-Jan-2016	1	First release.
15-Nov-2018	2	Updated <a href="#">Table 1. Absolute maximum ratings</a> , <a href="#">Table 2. Thermal data</a> , <a href="#">Table 4. On/off states</a> , <a href="#">Table 5. Dynamic</a> , <a href="#">Table 6. Switching times</a> , <a href="#">Table 7. Source drain diode</a> and <a href="#">Figure 7. Capacitance variations</a> .
11-Jun-2019	3	Updated description in cover page. Updated <a href="#">Table 5. Dynamic</a> and <a href="#">Table 6. Switching times</a> . Minor text changes.

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